SPECIFICATIONS

 $\begin{tabular}{ll} Insulation Resistance: & 500M\Omega min. at 500V DC \\ Withstanding Voltage: & 250V ACrms for 1 minute \\ \end{tabular}$

Contact Resistance: $100m\Omega$ max. at 10mA / 20mV max.

Current Rating: 0.5A

Voltage Rating. 5.0Vrms

Operating Temp. Range: -55°C to +85°C

Mating Cycles: 5,000 insertions

MATERIALS AND FINISH

Insulator: LCP

Contact: Copper Alloy, Ni-Au

FEATURES

- Conforms to GSM11.11 standard for the European mobile phone system
- Smooth extraction function by Push / Push mechanism

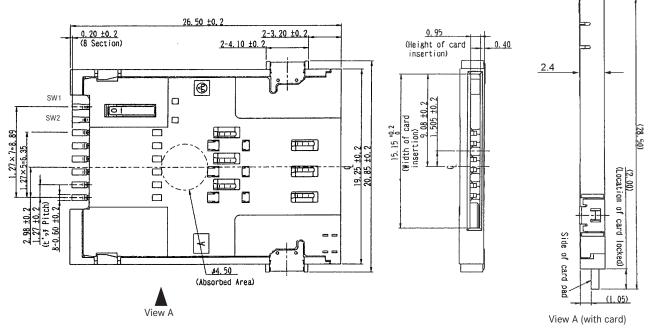
PART NUMBER





- · With and without switch
- For assembly on the bottom of the PC-Board
- Tape and Reel Packaging (800 pcs./reel)
- RoHS2011/65/EU

OUTLINE CONNECTOR DIMENSIONS



RECOMMENDED PCB LAYOUT (MOUNTING SIDE)

(26.50)2-3.00min. SW1 AND SW2 FOR FMS006Z-2101-0 ONLY 27×7-8.89 ±0.05 SW1 Center of C7 Connector C3 C6 51.6 Ċ2 14.45 - C5 CI 2. 98 ±0.05 1. 27 ±0.05 1. 37 ±0.05 1. 00 ±0.05 2-Pad for fixing metal Pads for terminal Outer dimension of Connector 2-2.95 ±0.05 2.30min. 19.55 ±0.05

CARD INSERTION

